

ABSTRACT OF THE DISCLOSURE

A method of constructing a microelectronic assembly as provided. A mold piece is locating over a microelectronic die carrying an integrated circuit. An encapsulant is injected into a space defined between surfaces of the mold piece and the microelectronic die. The encapsulant includes a liquid phase epoxy and a solid phase catalyst compound when injected. The encapsulant mixture is heated in the space to a temperature where the catalyst compound becomes a liquid and cures the epoxy. The catalyst compound may, for example, be polystyrene and the catalyst may be diphenyl phosphine. The catalyst compound is then heated to above its glass transition temperature so that the diphenyl phosphine is released from the polystyrene. The diphenyl phosphine then cures the epoxy. The epoxy is preferably a liquid at room temperature.